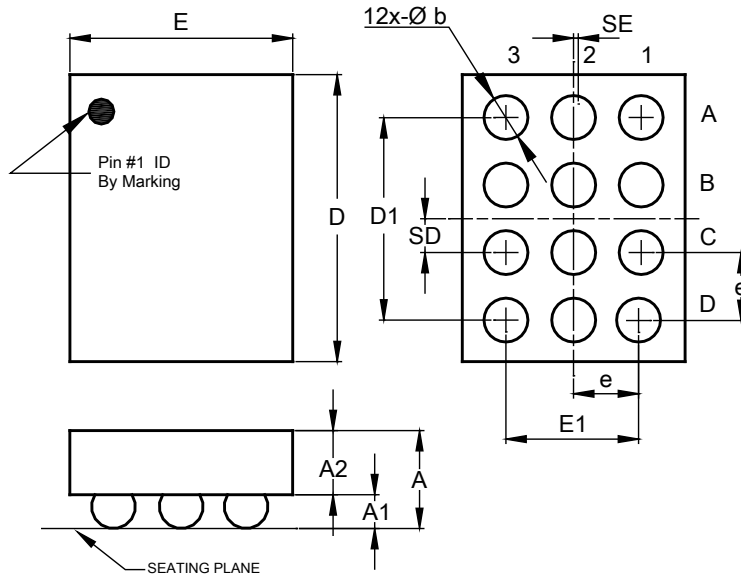


Package Outline Dimensions

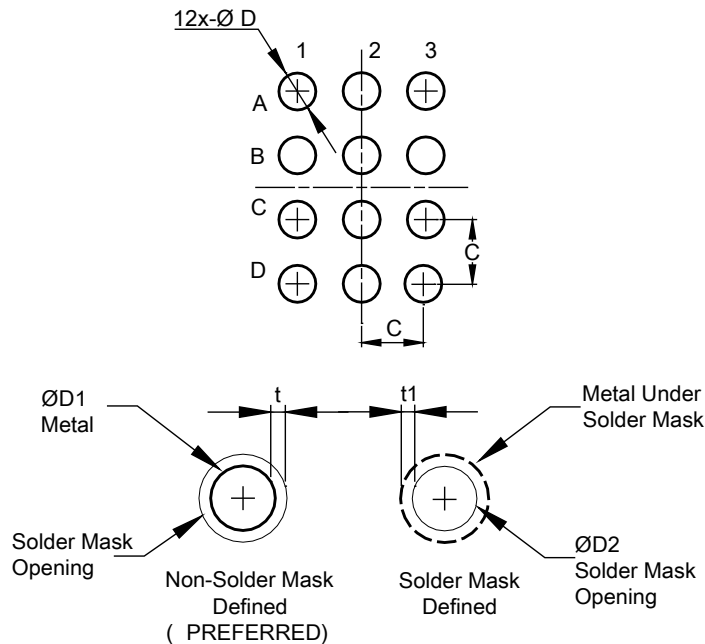
U-WLB1713-12



U-WLB1713-12			
Dim	Min	Max	Typ
A	0.525	0.625	0.575
A1	0.185	0.235	0.210
A2	0.340	0.390	0.365
b	0.220	0.300	0.260
D	1.690	1.750	1.720
D1	1.150	1.250	1.200
E	1.290	1.350	1.320
E1	0.750	0.850	0.800
e	0.400 BSC		
SD	0.200 BSC		
SE	0.000 BSC		
All Dimensions in mm			

Suggested Pad Layout

U-WLB1713-12



Dimensions	Value (in mm)
C	0.40
D	0.20
D1	0.20
D2	0.20
t	0.05 Max
t1	0.05 Min

SOLDER MASK DETAILS
(Not to Scale)

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.